

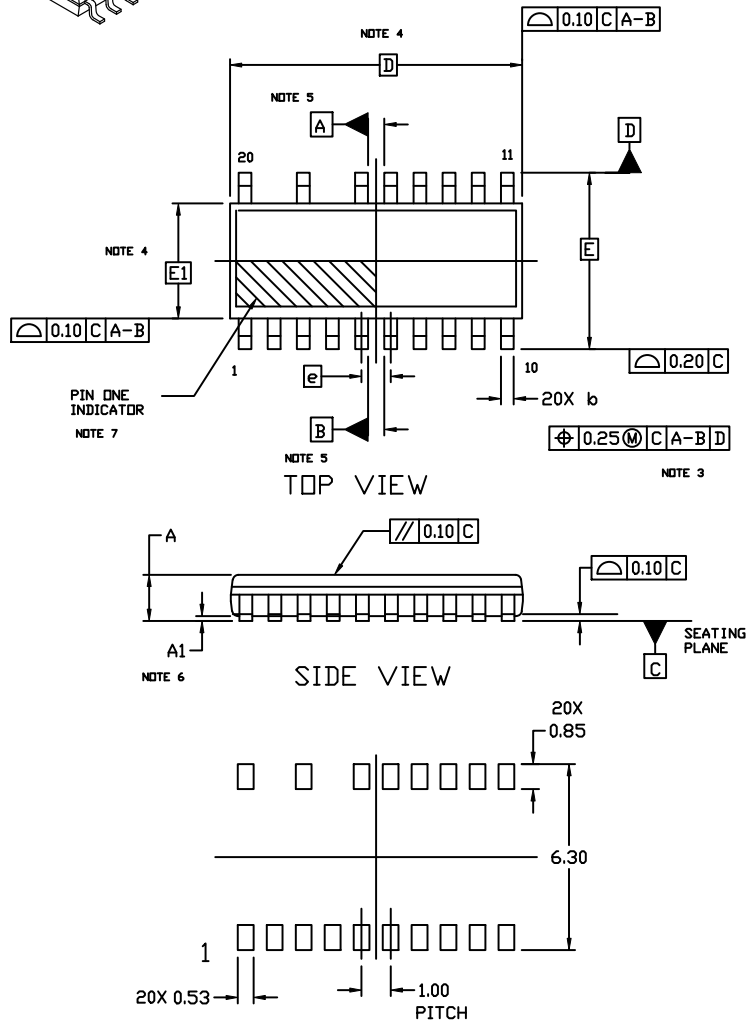
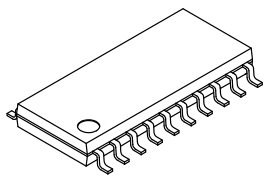
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®

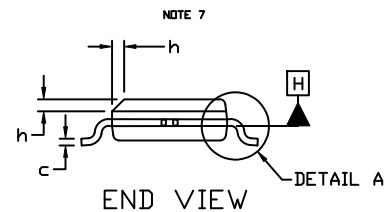


SOIC20 NB LESS PIN 17 & 19 CASE 751EZ ISSUE O

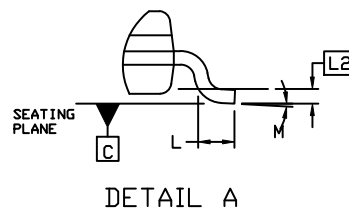
DATE 23 SEP 2019



1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION *b* DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.10 TOTAL IN EXCESS OF "*b*" DIMENSION. DIMENSION *b* APPLIES TO THE FLAT PORTION OF THE LEAD AND SHALL BE MEASURED BETWEEN 0.13 AND 0.25 FROM THE TIP.
4. DIMENSIONS *D* AND *E1* DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS BUT DO INCLUDE MOLD MISMATCH. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 mm PER SIDE. DIMENSIONS *D* AND *E1* ARE DETERMINED AT DATUM H.
5. DATUMS *A* AND *B* ARE TO BE DETERMINED AT DATUM H.
6. *A1* IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
7. CHAMFER FEATURE IS OPTIONAL. IF NOT PRESENT, THEN A PIN ONE IDENTIFIER MUST BE LOCATED IN THIS AREA.

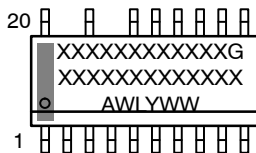


DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	---	---	1.70
A1	0.00	---	0.20
<i>b</i>	0.31	0.41	0.51
<i>c</i>	0.10	0.20	0.25
<i>D</i>	9.80	9.90	10.00
<i>E</i>	5.90	6.00	6.10
<i>E1</i>	3.80	3.90	4.00
<i>e</i>	1.00 BSC		
<i>h</i>	0.25	---	0.50
<i>L</i>	0.40	---	0.85
<i>L2</i>	0.25 REF		
<i>M</i>	0°	---	8°



RECOMMENDED MOUNTING FOOTPRINT
 For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERM/T.

GENERIC MARKING DIAGRAM*



- XXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "μ", may or may not be present. Some products may not follow the Generic Marking.

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